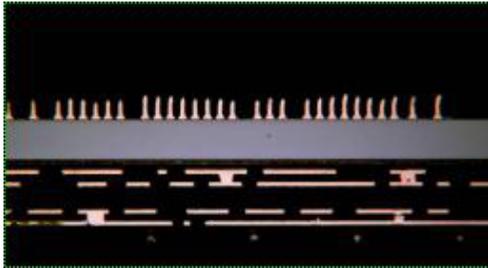
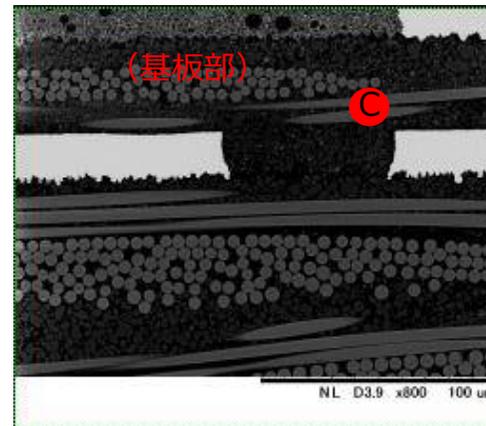
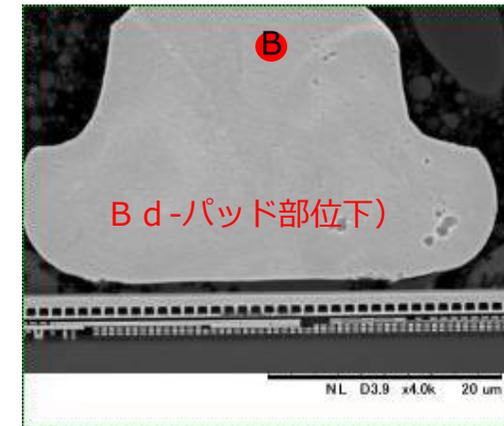
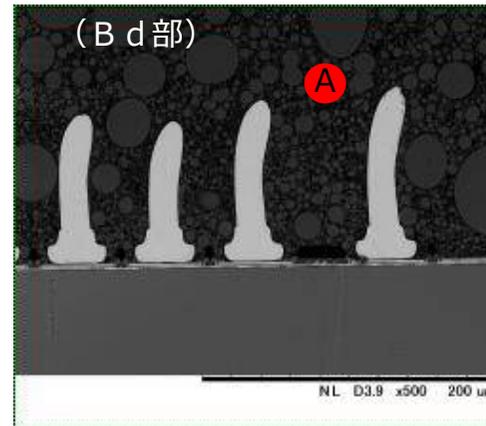
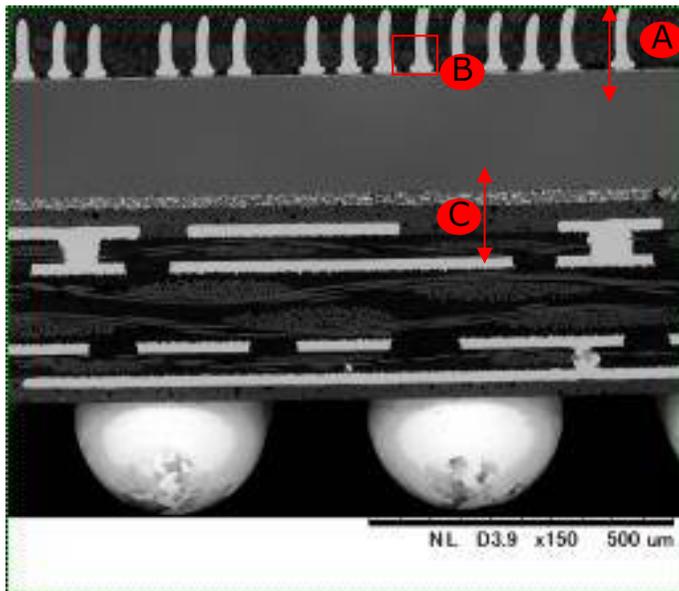


多層基板 I C P K G の断面研磨

研磨後の金顕観察



SEMによる断面構造観察



<各部位の観察>

<試料作製時間>
・ I S - P O L I S H E R で 2 時 間